## **APPENDIX**

## **VERSION WITH MARKINGS TO SHOW CHANGES MADE**

## IN THE SPECIFICATION:

The specification is changed as follows:

Please amend the paragraph bridging pages 8 and 9 as follows:

In order to form the rear substrate 12, data electrodes are formed on a glass substrate for the rear substrate (Step S6). Thereafter, a white reflective layer (dielectric layer) is formed on the whole surface (Step S7). Then, ribs 16 are formed to partition discharge cells (Step S8). A gap (discharge space) between the front and rear substrates is secured by the ribs 16. Thereafter, a phosphor that emits predetermined color light is applied onto side faces of ribs 16 and onto an exposed surface of the white reflective layer (Step S9). Thereafter, a glass frit (sealing frit) 13 made of, for example, amorphous glass with a low softening temperature is applied onto the edge of a display screen by use of a dispenser (Step S10). When the glass frit 13 is applied, a glass frit 13a is first applied continuously with a predetermined pattern, and a glass frit 13b is further applied thereon intermittently. As a result, a difference in the height of the glass frit 13 arises between the part where the glass frits 13a and 13b have been formed and the part where only the glass frit 13a has been applied. In other words, the glass frits 13a and 13b are applied onto the edge of the display screen of the rear substrate so as to produce a level difference. Thereafter, thermal treatment is carried out at about 500 °C both for baking of the phosphor and for prebaking of the glass frit (Step S11). Further, a glass tube (chip tube) 14 for exhaust is temporarily

fixed by a crystallized glass frit (fixing frit) 15 on the side of a surface different from the surface where the data electrodes and the like have been formed.

## **IN THE CLAIMS**:

chamber;

The claims are amended as follows:

Claim 1 (Amended) A method for manufacturing a plasma display panel, comprising the steps of:

laying a front substrate and a rear substrate on each other with a sealing frit therebetween;
heating said front substrate, said rear substrate and said sealing frit in a chamber and
exhausting impurity gas from both of said substrates by lowering internal pressure of said

melting said sealing frit in said chamber by further heating said front substrate, said rear substrate and said sealing frit after the pressure of said chamber reaches atmospheric pressure; and

solidifying said sealing frit in said chamber and sealing up said front substrate and said rear substrate.

Claim 12. (Amended) The method for manufacturing a plasma display panel according to claim 1, wherein said melting said sealing frit and said hardeningsolidifying said sealing frit each comprise a step of lowering internal pressure of said chamber.

Claim 13. (Amended) The method for manufacturing a plasma display panel according to claim 3, wherein said melting said sealing frit and said hardeningsolidifying said sealing frit each comprises a step of lowering internal pressure of said chamber.

Claim 14. (Amended) The method for manufacturing a plasma display panel according to claim 4, wherein said melting said sealing frit and said hardeningsolidifying said sealing frit each comprises a step of lowering internal pressure of said chamber.

Claim 15. (Amended) The method for manufacturing a plasma display panel according to claim 1, wherein said melting said sealing frit and said hardeningsolidifying said sealing frit each comprises a step of introducing at least one kind of gas selected from the group consisting of an oxygen gas, an inert gas, and dry air into said chamber.

Claim 16. (Amended) The method for manufacturing a plasma display panel according to claim 3, wherein said melting said sealing frit and said hardeningsolidifying said sealing frit each comprises a step of introducing at least one kind of gas selected from the group consisting of an oxygen gas, an inert gas, and dry air into said chamber.

Claim 17. (Amended) The method for manufacturing a plasma display panel according to claim 4, wherein said melting said sealing frit and said hardeningsolidifying said sealing frit each comprises a step of introducing at least one kind of gas selected from the group consisting

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of an oxygen gas, an inert gas, and dry air into said chamber.

New Claims 18-21 are added.